

## N-Channel Super Trench Power MOSFET

### Description

The RM12N100S8 uses **Super Trench** technology that is uniquely optimized to provide the most efficient high frequency switching performance. Both conduction and switching power losses are minimized due to an extremely low combination of  $R_{DS(ON)}$  and  $Q_g$ . This device is ideal for high-frequency switching and synchronous rectification.

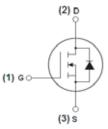
#### **General Features**

V<sub>DS</sub> =100V,I<sub>D</sub> =12A
R<sub>DS(ON)</sub>=8mΩ (typical) @ V<sub>GS</sub>=10V
R<sub>DS(ON)</sub>=11mΩ (typical) @ V<sub>GS</sub>=4.5V

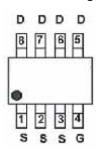
- Excellent gate charge x R<sub>DS(on)</sub> product(FOM)
- Very low on-resistance R<sub>DS(on)</sub>
- 150 °C operating temperature
- Pb-free lead plating
- 100% UIS tested

### Application

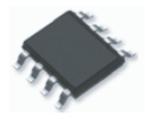
- DC/DC Converter
- Ideal for high-frequency switching and synchronous rectification
- Halogen-free



Schematic diagram



pin assignment



SOP-8 top view

### 100% UIS TESTED!

#### Package Marking and Ordering Information

J	5	J			
Device Marking	Device	Device Package	Reel Size	Tape width	Quantity
12N100	RM12N100S8	SOP-8	-	-	-

### Absolute Maximum Ratings (T<sub>A</sub>=25℃ unless otherwise noted)

Parameter	Symbol	Limit	Unit
Drain-Source Voltage	Vds	100	V
Gate-Source Voltage	Vgs	±20	V
Drain Current-Continuous	ID	12	А
Drain Current-Continuous(T <sub>C</sub> =100℃)	I <sub>D</sub> (100℃)	9	A
Maximum Power Dissipation	PD	3.1	W
Operating Junction and Storage Temperature Range	T <sub>J</sub> ,T <sub>STG</sub>	-55 To 150	°C

### **Thermal Characteristic**

Thermal Resistance, Junction-to-Ambient <sup>(Note 2)</sup>	R <sub>θJA</sub>	40	°C <b>/W</b>
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# Electrical Characteristics (T\_A=25 $^\circ\!\mathrm{C}$ unless otherwise noted)

Parameter	Symbol	Condition	Min	Тур	Мах	Unit
Off Characteristics		1	1			1
Drain-Source Breakdown Voltage	BV <sub>DSS</sub>	V <sub>GS</sub> =0V I <sub>D</sub> =250µA	100	-	-	V
Zero Gate Voltage Drain Current	I <sub>DSS</sub>	V <sub>DS</sub> =100V,V <sub>GS</sub> =0V	-	-	1	μA
Gate-Body Leakage Current	I <sub>GSS</sub>	V <sub>GS</sub> =±20V,V <sub>DS</sub> =0V	-	-	±100	nA
On Characteristics (Note2)						
Gate Threshold Voltage	V <sub>GS(th)</sub>	V <sub>DS</sub> =V <sub>GS</sub> ,I <sub>D</sub> =250µA	1.0	1.6	2.5	V
Drain-Source On-State Resistance		V <sub>GS</sub> =10V, I <sub>D</sub> =12A	-	8	10	mΩ
Drain-Source On-State Resistance	R <sub>DS(ON)</sub>	V <sub>GS</sub> =4.5V, I <sub>D</sub> =12A	-	11	13.2	mΩ
Forward Transconductance	<b>g</b> fs	V <sub>DS</sub> =10V,I <sub>D</sub> =10A	-	10	-	S
Dynamic Characteristics (Note3)		1				1
Input Capacitance	C <sub>lss</sub>		-	2250	-	PF
Output Capacitance	C <sub>oss</sub>	V <sub>DS</sub> =50V,V <sub>GS</sub> =0V, F=1.0MHz	-	410	-	PF
Reverse Transfer Capacitance	C <sub>rss</sub>	F=1.0MHZ	-	25	-	PF
Switching Characteristics (Note 3)		,				
Turn-on Delay Time	t <sub>d(on)</sub>		-	14.6	30	nS
Turn-on Rise Time	tr	$V_{DD}$ =50V,I <sub>D</sub> =1A,R <sub>L</sub> =6Ω,	-	21.5	44	nS
Turn-Off Delay Time	t <sub>d(off)</sub>	R <sub>G</sub> =1Ω,V <sub>GS</sub> =10V	-	54	108	nS
Turn-Off Fall Time	t <sub>f</sub>	-	-	83.3	168	nS
Total Gate Charge	Qg		-	37.8	76	nC
Gate-Source Charge	Q <sub>gs</sub>	I <sub>D</sub> =10A,V <sub>DD</sub> =50V,V <sub>GS</sub> =10V	-	7.8	-	nC
Gate-Drain Charge	Q <sub>gd</sub>	1	-	8.4	-	nC
Drain-Source Diode Characteristics						
Diode Forward Voltage (Note 2)	V <sub>SD</sub>	V <sub>GS</sub> =0V,I <sub>S</sub> =10A	-	-	1.0	V

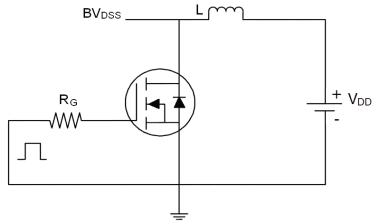
### Notes:

1. Repetitive Rating: Pulse width limited by maximum junction temperature. 2. Pulse Test: Pulse Width  $\leq$  300µs, Duty Cycle  $\leq$  2%.

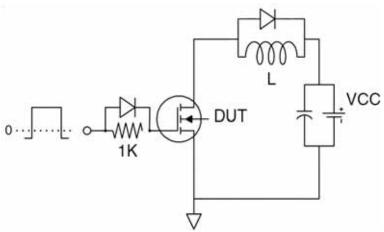
3. Guaranteed by design, not subject to production



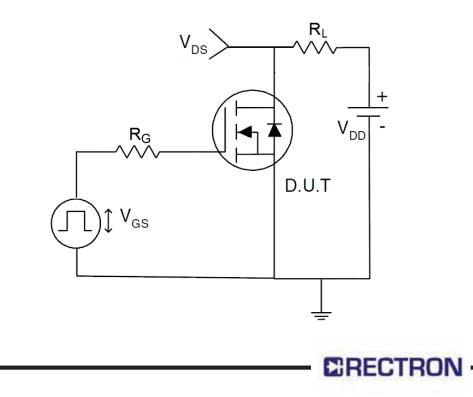
## Test Circuit 1) E<sub>AS</sub> test Circuit

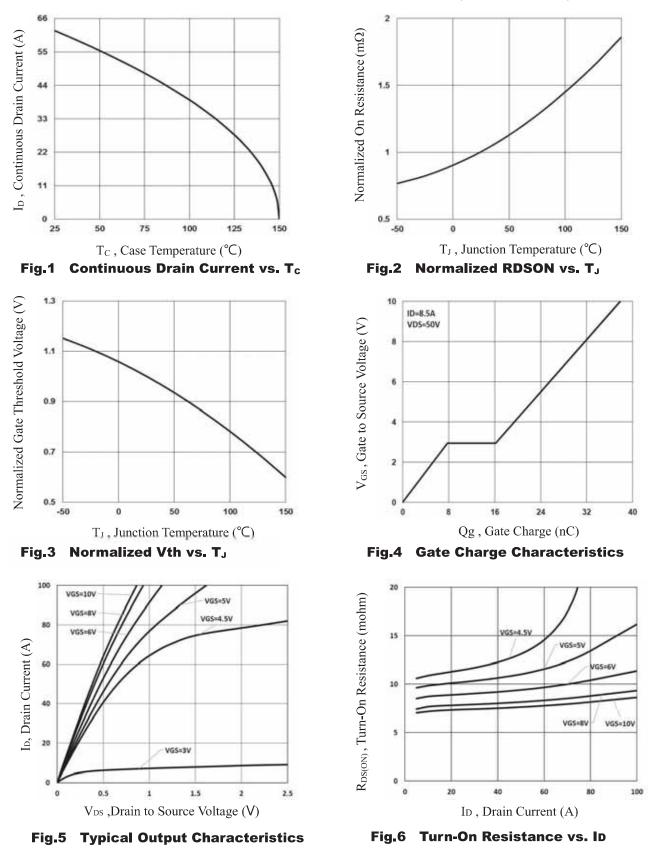


2) Gate charge test Circuit



3) Switch Time Test Circuit





### **RATING AND CHARACTERISTICS CURVES (RM12N100S8)**

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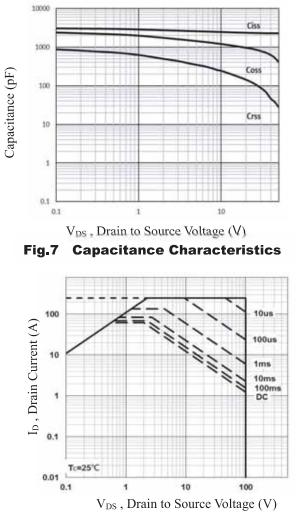


Fig.9 Maximum Safe Operation Area

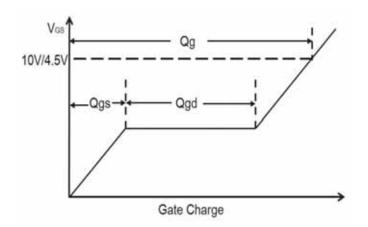


Fig.11 Gate Charge Waveform

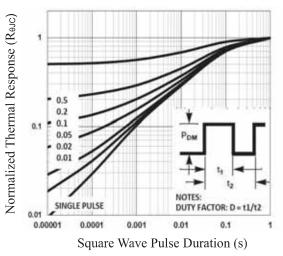


Fig.8 Normalized Transient Impedance

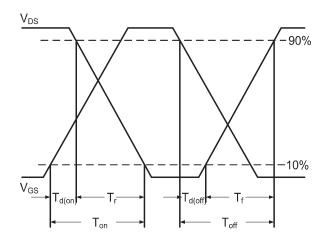
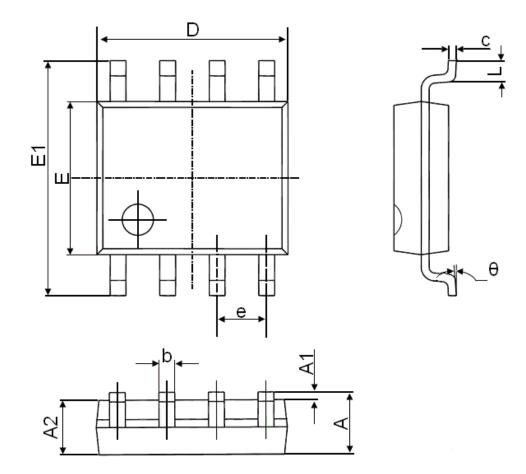


Fig.10 Switching Time Waveform



# SOP-8 Package Information



Symbol	Dimensions	In Millimeters	Dimensions In Inches		
Symbol	Min.	Max.	Min.	Max.	
A	1.350	1.750	0.053	0.069	
A1	0.100	0.250	0.004	0.010	
A2	1.350	1.550	0.053	0.061	
b	0.330	0.510	0.013	0.020	
с	0.170	0.250	0.006	0.010	
D	4.700	5.100	0.185	0.200	
E	3.800	4.000	0.150	0.157	
E1	5.800	6.200	0.228	0.244	
е	1.270(BSC)		0.050(BSC)		
L	0.400	1.270	0.016	0.050	
θ	0°	8°	0°	8°	



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